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# MC74LCX573

## Low-Voltage CMOS Octal Transparent Latch Flow Through Pinout

With 5 V-Tolerant Inputs and Outputs  
(3-State, Non-Inverting)

The MC74LCX573 is a high performance, non-inverting octal transparent latch operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_I$  specification of 5.5 V allows MC74LCX573 inputs to be safely driven from 5.0 V devices.

The MC74LCX573 contains 8 D-type latches with 3-state standard outputs. When the Latch Enable (LE) input is HIGH, data on the Dn inputs enters the latches. In this condition, the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state standard outputs are controlled by the Output Enable ( $\overline{OE}$ ) input. When  $\overline{OE}$  is LOW, the standard outputs are enabled. When  $\overline{OE}$  is HIGH, the standard outputs are in the high impedance state, but this does not interfere with new data entering into the latches. The LCX573 flow through design facilitates easy PC board layout.

### Features

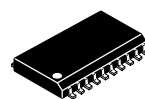
- Designed for 2.3 to 3.6 V  $V_{CC}$  Operation
- 5.0 V Tolerant - Interface Capability With 5.0 V TTL Logic
- Supports Live Insertion and Withdrawal
- $I_{OFF}$  Specification Guarantees High Impedance When  $V_{CC} = 0$  V
- LVTTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10  $\mu$ A)  
Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V  
Machine Model >200 V
- Pb-Free Packages are Available



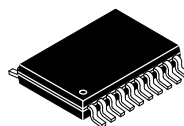
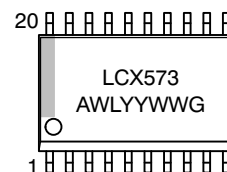
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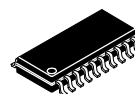
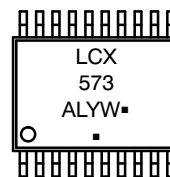
### MARKING DIAGRAMS



SOIC-20  
DW SUFFIX  
CASE 751D



TSSOP-20  
DT SUFFIX  
CASE 948E



SOEIAJ-20  
M SUFFIX  
CASE 967



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G = Pb-Free Package  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

# MC74LCX573

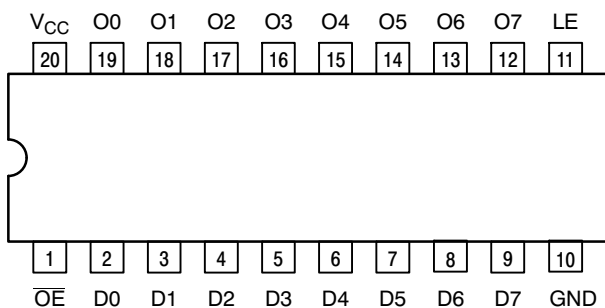


Figure 1. Pinout (Top View)

## PIN NAMES

PINS	FUNCTION
$\overline{OE}$	Output Enable Input
LE	Latch Enable Input
D0–D7	Data Inputs
O0–O7	3–State Latch Outputs

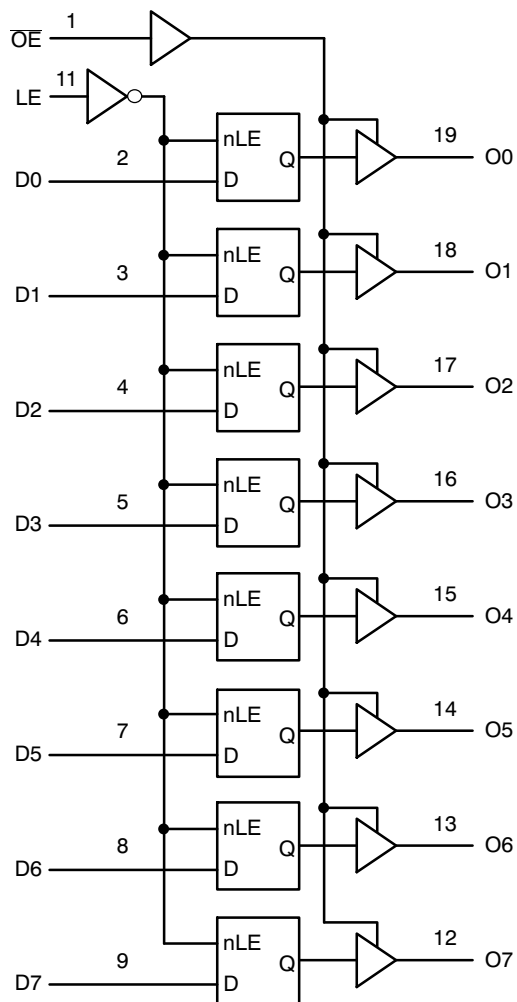


Figure 2. Logic Diagram

## TRUTH TABLE

INPUTS			OUTPUTS	OPERATING MODE
OE	LE	Dn	On	
L	H	H	H	Transparent (Latch Disabled); Read Latch
L	H	L	L	
L	L	h	H	Latched (Latch Enabled) Read Latch
L	L	l	L	
L	L	X	NC	Hold; Read Latch
H	L	X	Z	Hold; Disabled Outputs
H	H	H	Z	Transparent (Latch Disabled); Disabled Outputs
H	H	L	Z	
H	L	h	Z	Latched (Latch Enabled); Disabled Outputs
H	L	l	Z	

H = High Voltage Level;

h = High Voltage Level One Setup Time Prior to the Latch Enable High-to-Low Transition

L = Low Voltage Level

l = Low Voltage Level One Setup Time Prior to the Latch Enable High-to-Low Transition

NC = No Change, State Prior to the Latch Enable High-to-Low Transition

X = High or Low Voltage Level or Transitions are Acceptable

Z = High Impedance State

For  $I_{CC}$  Reasons DO NOT FLOAT Inputs

# MC74LCX573

## MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
V <sub>I</sub>	DC Input Voltage	-0.5 ≤ V <sub>I</sub> ≤ +7.0		V
V <sub>O</sub>	DC Output Voltage	-0.5 ≤ V <sub>O</sub> ≤ +7.0	Output in 3-State	V
		-0.5 ≤ V <sub>O</sub> ≤ V <sub>CC</sub> + 0.5	Output in HIGH or LOW State (Note 1)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	V <sub>O</sub> > V <sub>CC</sub>	mA
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I<sub>O</sub> absolute maximum rating must be observed.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V <sub>CC</sub>	Supply Voltage	Operating	2.0	2.5, 3.3	3.6	V
		Data Retention Only	1.5	2.5, 3.3	3.6	
V <sub>I</sub>	Input Voltage	0		5.5	V	
V <sub>O</sub>	Output Voltage (HIGH or LOW State) (3-State)	0		V <sub>CC</sub>	V	
		0		5.5		
I <sub>OH</sub>	HIGH Level Output Current	V <sub>CC</sub> = 3.0 V - 3.6 V		-24	mA	
		V <sub>CC</sub> = 2.7 V - 3.0 V		-12		
		V <sub>CC</sub> = 2.3 V - 2.7 V		-8		
I <sub>OL</sub>	LOW Level Output Current	V <sub>CC</sub> = 3.0 V - 3.6 V		+24	mA	
		V <sub>CC</sub> = 2.7 V - 3.0 V		+12		
		V <sub>CC</sub> = 2.3 V - 2.7 V		+8		
T <sub>A</sub>	Operating Free-Air Temperature	-55		+125	°C	
Δt/ΔV	Input Transition Rise or Fall Rate, V <sub>IN</sub> from 0.8 V to 2.0 V, V <sub>CC</sub> = 3.0 V	0		10	ns/V	

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74LCX573DW	SOIC-20	38 Units / Rail
MC74LCX573DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74LCX573DWR2	SOIC-20	1000 Tape & Reel
MC74LCX573DWR2G	SOIC-20 (Pb-Free)	1000 Tape & Reel
MC74LCX573DT	TSSOP-20*	75 Units / Rail
MC74LCX573DTG	TSSOP-20*	75 Units / Rail
MC74LCX573DTR2	TSSOP-20*	2000 Tape & Reel
MC74LCX573DTR2G	TSSOP-20*	2000 Tape & Reel
MC74LCX573M	SOEIAJ-20	40 Units / Rail
MC74LCX573MG	SOEIAJ-20 (Pb-Free)	40 Units / Rail
MC74LCX573MEL	SOEIAJ-20	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

# MC74LCX573

## DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -55°C to +125°C		Unit
			Min	Max	Min	Max	
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V	1.7		1.7		V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0		2.0		
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V		0.7		0.7	V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8		0.8	
V <sub>OH</sub>	HIGH Level Output Voltage	2.3 V ≤ V <sub>CC</sub> ≤ 3.6 V; I <sub>OL</sub> = 100 μA	V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 2.3 V; I <sub>OH</sub> = -8 mA	1.8		1.8		
		V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA	2.2		2.2		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4		2.4		
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2		2.2		
V <sub>OL</sub>	LOW Level Output Voltage	2.3 V ≤ V <sub>CC</sub> ≤ 3.6 V; I <sub>OL</sub> = 100 μA		0.2		0.2	V
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 8 mA		0.6		0.6	
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55		0.60	
I <sub>I</sub>	Input Leakage Current	2.3 V ≤ V <sub>CC</sub> ≤ 3.6 V; 0 V ≤ V <sub>I</sub> ≤ 5.5 V		±5		±5	μA
I <sub>OZ</sub>	3-State Output Current	2.3 ≤ V <sub>CC</sub> ≤ 3.6 V; 0V ≤ V <sub>O</sub> ≤ 5.5 V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>		±5		±5	μA
I <sub>OFF</sub>	Power-Off Leakage Current	V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> = 5.5 V		10		10	μA
I <sub>CC</sub>	Quiescent Supply Current	2.3 ≤ V <sub>CC</sub> ≤ 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub>		10		10	μA
		2.3 ≤ V <sub>CC</sub> ≤ 3.6 V; 3.6 ≤ V <sub>I</sub> or V <sub>O</sub> ≤ 5.5 V		±10		±10	
ΔI <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	2.3 ≤ V <sub>CC</sub> ≤ 3.6 V; V <sub>IH</sub> = V <sub>CC</sub> - 0.6 V		500		500	μA

2. These values of V<sub>I</sub> are used to test DC electrical characteristics only.

## AC CHARACTERISTICS t<sub>R</sub> = t<sub>F</sub> = 2.5 ns; R<sub>L</sub> = 500 Ω

Symbol	Parameter	Waveform	Limits						Unit
			T <sub>A</sub> = -55°C to +125°C						
			V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		
			C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		
		Min	Max	Min	Max	Min	Max		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay D <sub>n</sub> to O <sub>n</sub>	1	1.5	8.0	1.5	9.0	1.5	9.6	ns
			1.5	8.0	1.5	9.0	1.5	9.6	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay LE to O <sub>n</sub>	3	1.5	8.5	1.5	9.5	1.5	10.5	ns
			1.5	8.5	1.5	9.5	1.5	10.5	
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable Time to HIGH and LOW Level	2	1.5	8.5	1.5	9.5	1.5	10.5	ns
			1.5	8.5	1.5	9.5	1.5	10.5	
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable Time From High and Low Level	2	1.5	6.5	1.5	7.0	1.5	7.8	ns
			1.5	6.5	1.5	7.0	1.5	7.8	
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to LE	3	2.5		2.5		4.0		
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to LE	3	1.5		1.5		2.0		
t <sub>w</sub>	LE Pulse Width, HIGH	3	3.3		3.3		4.0		
t <sub>OSHL</sub> t <sub>OSLH</sub>	Output-to-Output Skew (Note 3)			1.0				ns	

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

# MC74LCX573

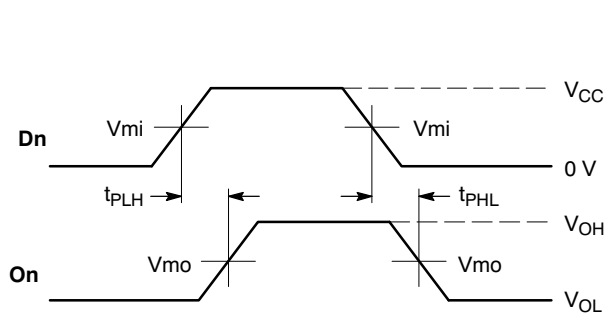
## DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	T <sub>A</sub> = +25°C			Unit
			Min	Typ	Max	
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	V <sub>CC</sub> = 3.3 V, C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3 V, V <sub>IL</sub> = 0 V V <sub>CC</sub> = 2.5 V, C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5 V, V <sub>IL</sub> = 0 V		0.8 0.6		V V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	V <sub>CC</sub> = 3.3 V, C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3 V, V <sub>IL</sub> = 0 V V <sub>CC</sub> = 2.5 V, C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5 V, V <sub>IL</sub> = 0 V		-0.8 -0.6		V V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

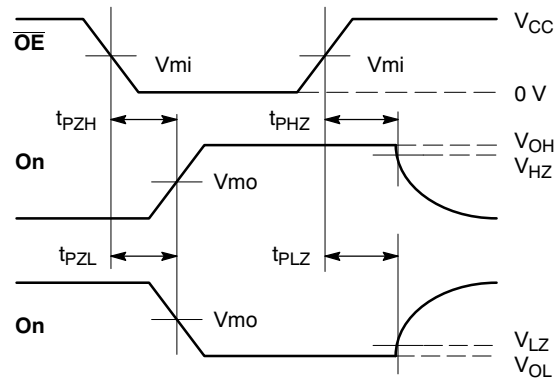
## CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	7	pF
C <sub>I/O</sub>	Input/Output Capacitance	V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF



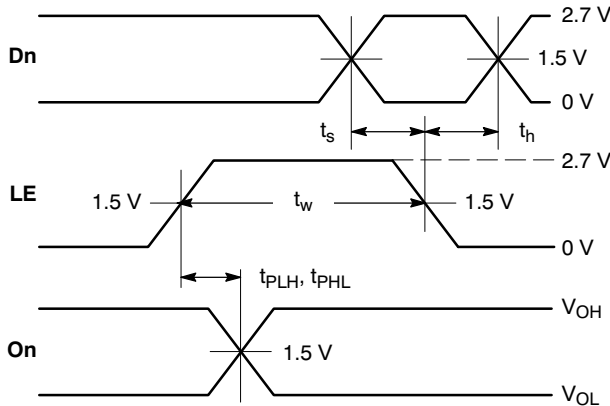
**WAVEFORM 1 - PROPAGATION DELAYS**

t<sub>R</sub> = t<sub>F</sub> = 2.5 ns, 10% to 90%; f = 1 MHz; t<sub>W</sub> = 500 ns



**WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES**

t<sub>R</sub> = t<sub>F</sub> = 2.5 ns, 10% to 90%; f = 1 MHz; t<sub>W</sub> = 500 ns



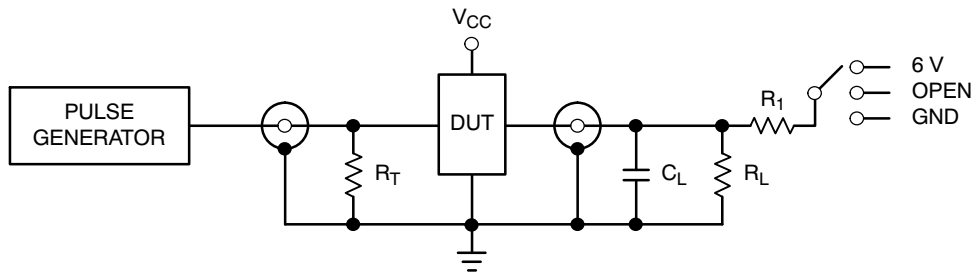
**WAVEFORM 3 - LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn to LE SETUP AND HOLD TIMES**

t<sub>R</sub> = t<sub>F</sub> = 2.5 ns, 10% to 90%; f = 1 MHz; t<sub>W</sub> = 500 ns except when noted

Symbol	V <sub>CC</sub>		
	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V
V <sub>mi</sub>	1.5 V	1.5 V	V <sub>CC</sub> /2
V <sub>mo</sub>	1.5 V	1.5 V	V <sub>CC</sub> /2
V <sub>HZ</sub>	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.15 V
V <sub>LZ</sub>	V <sub>OL</sub> - 0.3 V	V <sub>OL</sub> - 0.3 V	V <sub>OL</sub> - 0.15 V

**Figure 3. AC Waveforms**

# MC74LCX573



TEST	SWITCH
$t_{PLH}$ , $t_{PHL}$	Open
$t_{PZL}$ , $t_{PLZ}$	6 V at $V_{CC} = 3.3 \pm 0.3$ V 6 V at $V_{CC} = 2.5 \pm 0.2$ V
Open Collector/Drain $t_{PLH}$ and $t_{PHL}$	6 V
$t_{PZH}$ , $t_{PHZ}$	GND

$C_L = 50$  pF at  $V_{CC} = 3.3 \pm 0.3$  V or equivalent (includes jig and probe capacitance)

$C_L = 30$  pF at  $V_{CC} = 2.5 \pm 0.2$  V or equivalent (includes jig and probe capacitance)

$R_L = R_1 = 500 \Omega$  or equivalent

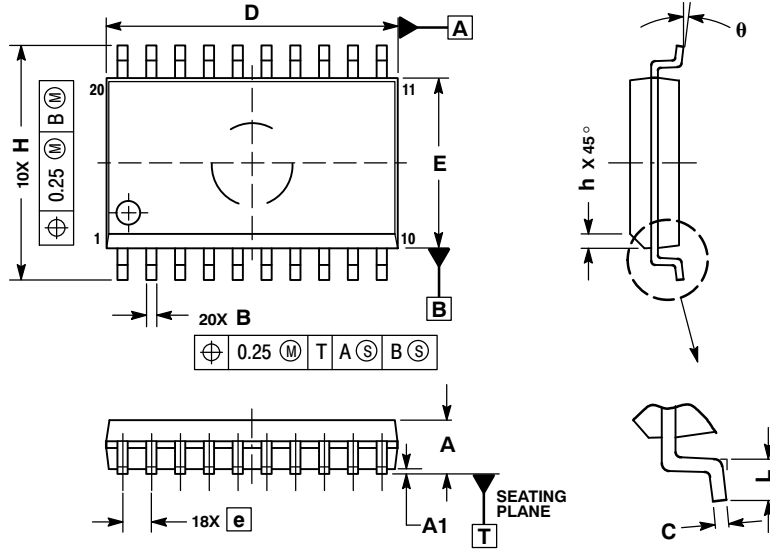
$R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

**Figure 4. Test Circuit**

# MC74LCX573

## PACKAGE DIMENSIONS

SO-20 WB  
CASE 751D-05  
ISSUE G



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

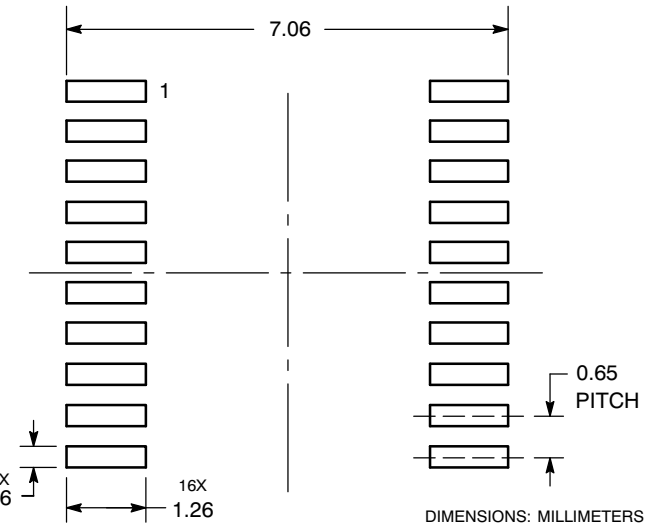
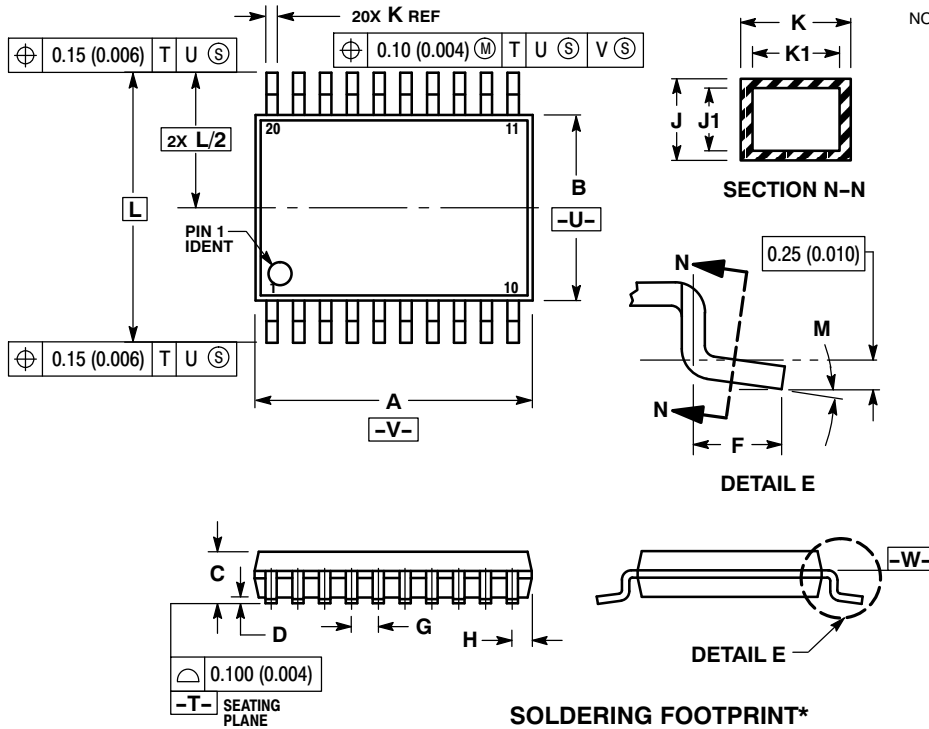
DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
theta	0°	7°



# MC74LCX573

## PACKAGE DIMENSIONS

TSSOP-20  
CASE 948E-02  
ISSUE C

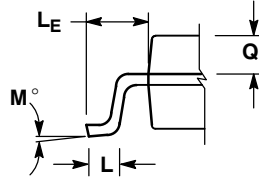
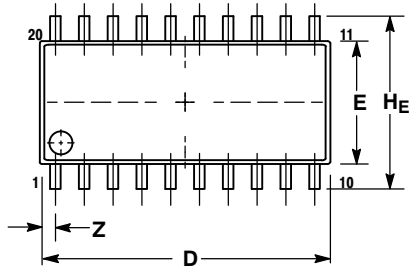


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

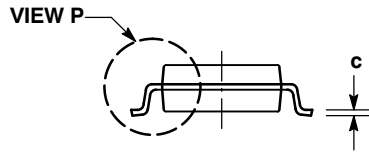
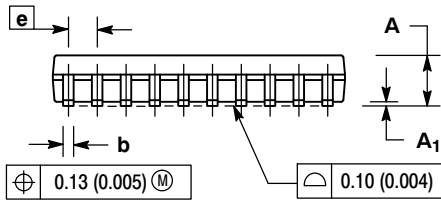
# MC74LCX573

## PACKAGE DIMENSIONS

SOEIAJ-20  
CASE 967-01  
ISSUE A



DETAIL P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 <sup>o</sup>	10 <sup>o</sup>	0 <sup>o</sup>	10 <sup>o</sup>
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

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